## **TYPICAL SPECIFICATIONS**

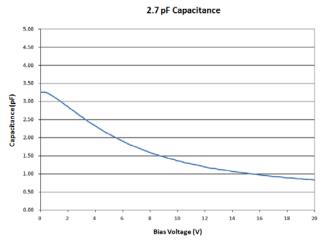
## Representative Performance Data at 25°C

**Table 1. PERFORMANCE DATA** 

Parameter	Min	Тур	Max	Units
Operating Bias Voltage	2.0		20	V
Capacitance (V <sub>bias</sub> = 2 V)	2.32	2.70	2.97	pF
Capacitance (V <sub>bias</sub> = 20 V)	0.73	0.77	0.81	pF
Tuning Range (2 V - 20 V)	3.00	3.50	4.05	
Tuning Range (20 V - 2 V)	2.80	3.30	4.05	
Leakage Current (Wafer Level)		270	540	nA
Leakage Current (WLCSP)			4.0	μΑ
Operating Frequency	700		2400	MHz
Quality Factor @ 900 MHz, 2 V		90		
Quality Factor @ 900 MHz, 20 V		90		
Quality Factor @ 1800 MHz, 2 V		70		
Quality Factor @ 1800 MHz, 20 V		70		
IP3 (V <sub>bias</sub> = 2 V) <sup>[1,3]</sup>		68		dBm
IP3 (V <sub>bias</sub> = 20 V) <sup>[1,3]</sup>		82		dBm
2nd Harmonic (V <sub>bias</sub> = 2 V) <sup>[2,3]</sup>		-61		dBm
2nd Harmonic (V <sub>bias</sub> = 20 V) [2,3]		-68		dBm
3rd Harmonic (V <sub>bias</sub> = 2 V) <sup>[2,3]</sup>		-38		dBm
3rd Harmonic (V <sub>bias</sub> = 20 V) <sup>[2,3]</sup>		-62		dBm
Transition Time (Cmin $\rightarrow$ Cmax) [4]		80		μS
Transition Time (Cmax → Cmin) [4]		70		μS

<sup>1.</sup>  $f_1$  = 850 MHz,  $f_2$  = 860 MHz, Pin 25 dBm/Tone 2. 850 MHz, Pin +34 dBm 3. IP3 and Harmonics are measured in the shunt configuration in a 50  $\Omega$  environment 4. RF1 and RF2 are both connected to DC ground

## Representative performance data at 25°C for 2.7 pF WLCSP Package

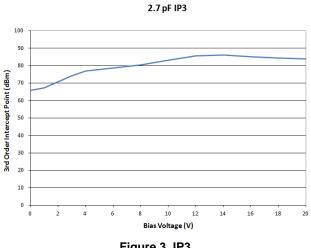


-10 Harmonic Power (dBm) -50 -80

2.7 pF Harmonic Power

Figure 1. Capacitance

Figure 2. Harmonic Power



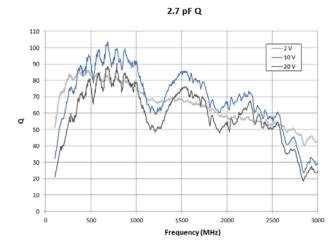


Figure 3. IP3

Figure 4. Q

#### **Table 2. ABSOLUTE MAXIMUM RATINGS**

Parameter	Rating	Units
Input Power	+40	dBm
Bias Voltage	+25 (Note 5)	V
Operating Temperature Range	-30 to +85	°C
Storage Temperature Range	-55 to +125	°C
ESD – Human Body Model	Class 1A JEDEC HBM Standard (Note 6)	

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

- 5. WLCSP: Recommended Bias Voltage not to exceed 20 V
- 6. Class 1A defined as passing 250 V, but may fail after exposure to 500 V ESD pulse

#### **ASSEMBLY CONSIDERATIONS AND REFLOW PROFILE**

The following assembly considerations should be observed:

#### Cleanliness

These chips should be handled in a clean environment.

#### **Electro-static Sensitivity**

ON Semiconductor's PTICs are ESD Class 1A sensitive. The proper ESD handling procedures should be used.

#### Mounting

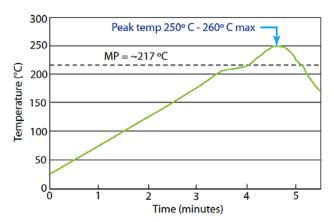
The WLCSP PTIC is fabricated for Flip Chip solder mounting. Connectivity to the RF and Bias terminations on the PTIC die is established through copper pillar posts (53  $\mu$ m nominal height) topped with lead-free SAC351 solder caps (28  $\mu$ m nominal height). The PTIC die is RoHS-compliant and compatible with lead-free soldering profile.

## **Post-reflow Cleaning**

Use of ultrasonic cleaning is not recommended for pillared devices as it may lead to premature fatigue failure of the pillars.

#### Molding

The PTIC die is compatible for over-molding or under-fill.



This reflow profile is a guideline for Pb-free solder materials. Adjustments to this profile are necessary based on specific process requirements and board size, thickness and density. Not to exceed 260° C for 5 seconds.

Figure 5. Reflow Profile

#### ORIENTATION OF THE PTIC FOR OPTIMUM LOSSES

When configuring the PTIC in your specific circuit design, at least one of the RF terminals must be connected to DC ground. If minimum transition times are required, DC ground on both RF terminals is recommended. To minimize losses, the PTIC should be oriented such that RF2 is at the lower RF impedance of the two RF nodes. A shunt PTIC, for example, should have RF2 connected to RF ground.

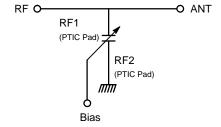


Figure 6. PTIC Orientation Functional Block Diagram

## **PART NUMBER DEFINITION**

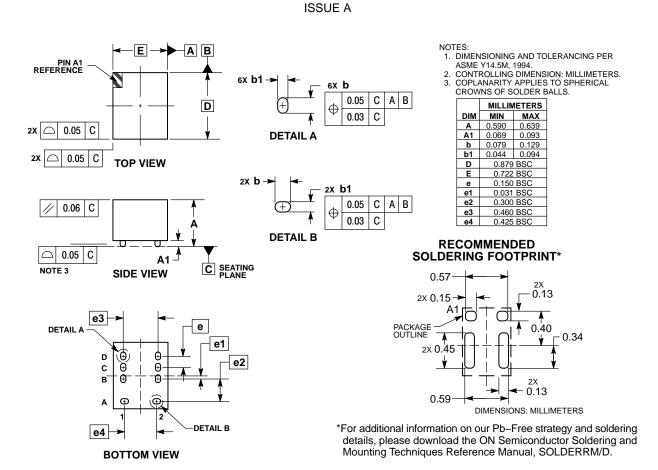
**Table 3. PART NUMBERS** 

	Capacitance		
Part Number	2 V	20 V	Package
TCP-3027N-DT	2.70	0.77	8-Pillar WLCSP
TCP-3027N-QT	2.70	0.77	6-Pin QFN

For information on device numbering and ordering codes, please download the *Device Nomenclature* technical note (TND310/D) from <a href="https://www.onsemi.com">www.onsemi.com</a>.

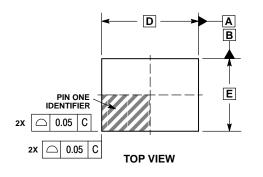
## PACKAGE DIMENSIONS

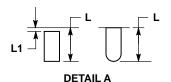
## WLCSP8, 0.88x0.72 CASE 567KC



#### PACKAGE DIMENSIONS

### QFN6 1.6x1.2, 0.5P CASE 485DX **ISSUE O**







#### MILLIMETERS DIM MIN MAX 1.00 0.00 0.05 0.15 REF А3 0.22 0.28 b 1.60 BSC 1.20 BSC 0.50 BSC 0.39 0.46 0.15

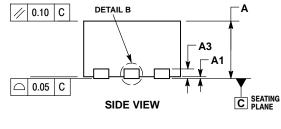
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ASME Y14.5M, 1994. CONTROLLING DIMENSION: MILLIMETERS

**EXPOSED Cu** 

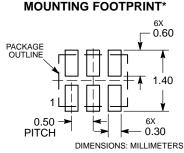
**DETAIL B** 

ALTERNATE CONSTRUCTIONS

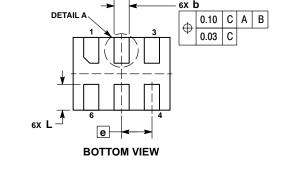




NOTES



\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.



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